

Data Sheet December 15, 2011 FN481.7

General Purpose High Current NPN Transistor Array

The CA3083 is a versatile array of five high current (to 100mA) NPN transistors on a common monolithic substrate. In addition, two of these transistors (Q_1 and Q_2) are matched at low current (i.e., 1mA) for applications in which offset parameters are of special importance.

Independent connections for each transistor plus a separate terminal for the substrate permit maximum flexibility in circuit design.

Ordering Information

| PART NUMBER | PART MARKING | TEMP. RANGE (°C) | PACKAGE | PKG. DWG.# |
|----------------------|-----------------|------------------------|---------------------------------------|---------------|
| CA3083 | CA3083 | -55 to 125 | 16 Ld PDIP | E16.3 |
| CA3083Z (Note) | CA3083Z | -55 to 125 | 16 Ld PDIP* (Pb-free) | E16.3 |
| CA3083M96 | 3083 | -55 to 125 | 16 Ld SOIC Tape and Reel | M16.15 |
| CA3083MZ (Note) | 3083MZ | -55 to 125 | 16 Ld SOIC (Pb-Free) | M16.15 |
| CA3083MZ96 (Note) | 3083MZ | -55 to 125 | 16 Ld SOIC (Pb-Free) Tape and Reel | M16.15 |

^{*}Pb-free PDIPs can be used for through hole wave solder processing only. They are not intended for use in Reflow solder processing applications.

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Features

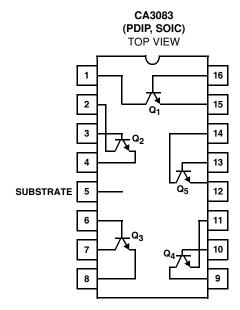
| • | High I _C |
|---|---|
| • | Low V _{CE sat} (at 50mA) |
| • | Matched Pair (Q ₁ and Q ₂) |
| | - V _{IO} (V _{BE} Match)±5mV (Max) |
| | - I _{IO} (at 1mA) 2.5μA (Max) |

- 5 Independent Transistors Plus Separate Substrate Connection
- · Pb-Free Plus Anneal Available (RoHS Compliant)

Applications

- Signal Processing and Switching Systems Operating from DC to VHF
- · Lamp and Relay Driver
- · Differential Amplifier
- · Temperature Compensated Amplifier
- Thyristor Firing
- See Application Note AN5296 "Applications of the CA3018 Circuit Transistor Array" for Suggested Applications

Pinout



Absolute Maximum Ratings

| The following ratings apply for each transistor in the device: | |
|--|------|
| Collector-to-Emitter Voltage, V _{CEO} | 15V |
| Collector-to-Base Voltage, V _{CBO} | |
| Collector-to-Substrate Voltage, V _{CIO} (Note 1) | 20V |
| Emitter-to-Base Voltage, V _{EBO} | . 5V |
| Collector Current (I _C) | 00mA |
| Base Current (I _B) | 20mA |

Thermal Information

| Thermal Resistance (Typical, Note 2) | θ _{JA} (°C/W) | θ _{JC} (°C/W) |
|---|------------------------|------------------------|
| PDIP Package | 135 | N/A |
| SOIC Package | 200 | N/A |
| Maximum Power Dissipation (Any One Tra | ansistor) | 500mW |
| Maximum Junction Temperature (Plastic F | ackage) | 150°C |
| Maximum Storage Temperature Range | 6 | 5°C to 150°C |
| Maximum Lead Temperature (Soldering 1 | 0s) | 300°C |
| (SOIC - Lead Tips Only) | | |

Operating Conditions

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

- 1. The collector of each transistor of the CA3083 is isolated from the substrate by an integral diode. The substrate must be connected to a voltage which is more negative than any collector voltage in order to maintain isolation between transistors and provide normal transistor action. To avoid undesired coupling between transistors, the substrate Terminal (5) should be maintained at either DC or signal (AC) ground. A suitable bypass capacitor can be used to establish a signal ground.
- 2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications For Equipment Design, T_A = 25°C

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN | TYP | MAX | UNITS |
|---|----------------------|---|-----------------------|------|------|------|-------|
| FOR EACH TRANSISTOR | | | | | | | |
| Collector-to-Base Breakdown Voltage | V _{(BR)CBO} | $I_{C} = 100 \mu A, I_{E} = 0$ | | 20 | 60 | - | V |
| Collector-to-Emitter Breakdown Voltage | V _{(BR)CEO} | $V_{(BR)CEO}$ $I_C = 1mA, I_B = 0$ | | 15 | 24 | - | V |
| Collector-to-Substrate Breakdown Voltage | V _{(BR)CIO} | $I_{CI} = 100\mu A, I_B = 0, I_E = 0$ | | 20 | 60 | - | V |
| Emitter-to-Base Breakdown Voltage | V _{(BR)EBO} | $I_E = 500 \mu A, I_C = 0$ | | 5 | 6.9 | - | V |
| Collector-Cutoff-Current | I _{CEO} | V _{CE} = 10V, I _B = 0 | | - | - | 10 | μА |
| Collector-Cutoff-Current | I _{CBO} | V _{CB} = 10V, I _E = 0 | | - | - | 1 | μА |
| DC Forward-Current Transfer Ratio (Note 3) (Figure 1) | h _{FE} | V _{CE} = 3V | I _C = 10mA | 40 | 76 | - | |
| | | | I _C = 50mA | 40 | 75 | - | |
| Base-to-Emitter Voltage (Figure 2) | V _{BE} | V _{CE} = 3V, I _C = 10mA | | 0.65 | 0.74 | 0.85 | V |
| Collector-to-Emitter Saturation Voltage (Figures 3, 4) | V _{CE SAT} | $I_C = 50$ mA, $I_B = 5$ mA | | - | 0.40 | 0.70 | ٧ |
| Gain Bandwidth Product | f _T | V _{CE} = 3V, I _C = 10mA | | - | 450 | - | MHz |
| FOR TRANSISTORS Q ₁ AND Q ₂ (As a Differential Am | plifier) | 1 | | | | | |
| Absolute Input Offset Voltage (Figure 6) | V _{IO} | V _{CE} = 3V, I _C = 1mA | | - | 1.2 | 5 | mV |
| Absolute Input Offset Current (Figure 7) | I _{IO} | V _{CE} = 3V, I _C = 1mA | | - | 0.7 | 2.5 | μΑ |

NOTE:

3. Actual forcing current is via the emitter for this test.

Typical Performance Curves

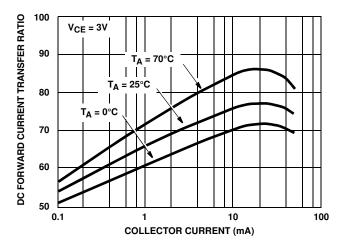


FIGURE 1. hFE vs IC

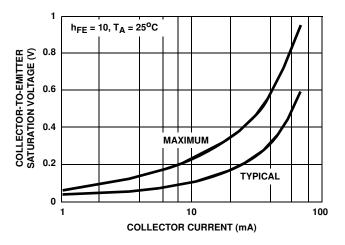


FIGURE 3. V_{CE SAT} vs I_C

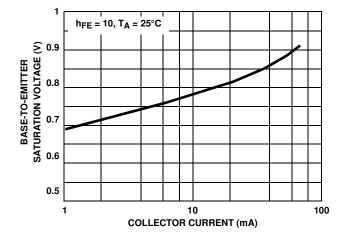


FIGURE 5. VBE SAT VS IC

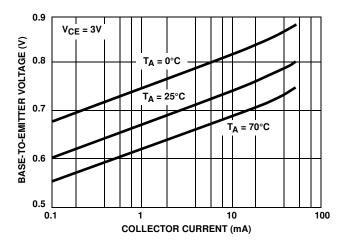


FIGURE 2. V_{BE} vs I_C

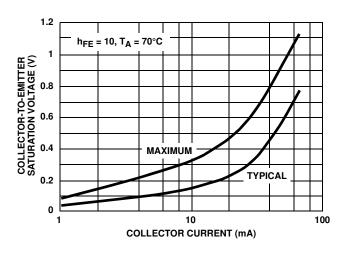


FIGURE 4. V_{CE SAT} vs I_C

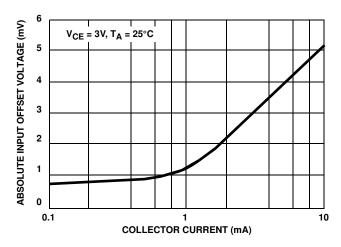


FIGURE 6. V_{IO} vs I_C (TRANSISTORS Q_1 AND Q_2 AS A DIFFERENTIAL AMPLIFIER)

Typical Performance Curves (Continued)

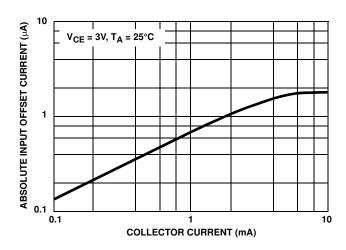


FIGURE 7. I_{IO} vs I_C (TRANSISTORS Q₁ AND Q₂ AS A DIFFERENTIAL AMPLIFIER)

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